T-46-09-05

MOTOROLA

MC14014B
MC14021B

CMOS MSI

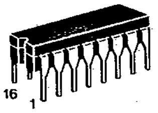
(LOW-POWER COMPLEMENTARY MOS)

8-BIT STATIC SHIFT REGISTER

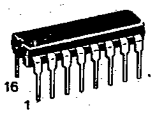
8-BIT STATIC SHIFT REGISTER

The MC14014B and MC14021B 8-bit static shift registers are constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. These shift registers find primary use in parallel-to-serial data conversion, synchronous and asynchronous parallel input, serial output data queueing; and other general purpose register applications requiring low power and/or high noise immunity.

- Synchronous Parallel Input/Serial Output (MC14014B)
- Asynchronous Parallel Input/Serial Output (MC14021B)
- Synchronous Serial Input/Serial Output
- Full Static Operation
- "Q" Outputs from Sixth, Seventh, and Eighth Stages
- Double Diode Input Protection
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- MC14014B Pin-for-Pin Replacement for CD4014B
- MC14021B Pin-for-Pin Replacement for CD4021B



L SUFFIX
CERAMIC PACKAGE
CASE 620



P SUFFIX
PLASTIC PACKAGE
CASE 648

ORDERING INFORMATION

A Series: −55°C to +125°C
MC14XXXBAL (Ceramic Package Only)

C Series: −40°C to +85°C
MC14XXXBCP (Plastic Package)
MC14XXXBCL (Ceramic Package)

MAXIMUM RATINGS* (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage	−0.5 to +18.0	V
V_{in}, V_{out}	Input or Output Voltage (DC or Transient)	−0.5 to V_{DD} +0.5	V
I_{in}, I_{out}	Input or Output Current (DC or Transient), per Pin	±10	mA
P_D	Power Dissipation, per Package†	500	mW
T_{stg}	Storage Temperature	−65 to +150	°C
T_L	Lead Temperature (8-Second Soldering)	260	°C

*Maximum Ratings are those values beyond which damage to the device may occur.
†Temperature Derating: Plastic "P" Package: −12mW/°C from 65°C to 85°C
Ceramic "L" Package: −12mW/°C from 100°C to 125°C

TRUTH TABLE

SERIAL OPERATION:

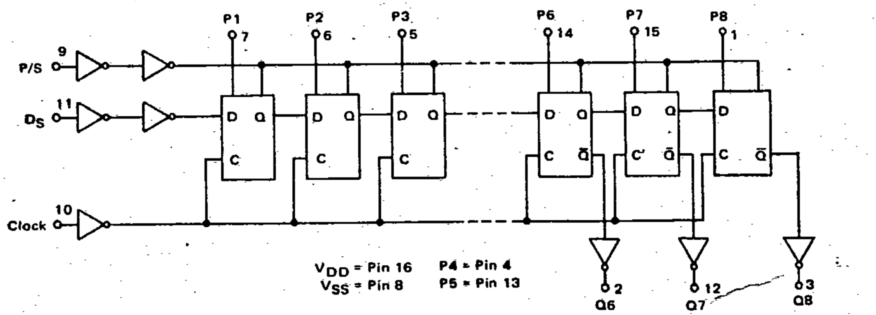
t	CLOCK	D_S	P/S	Q6 t = n+6	Q7 t = n+7	Q8 t = n+8
n	↑	0	0	0	?	?
n+1	↑	1	0	1	0	?
n+2	↑	0	0	0	1	0
n+3	↑	1	0	1	0	1
	↓	X	0	Q6	Q7	Q8

PARALLEL OPERATION:

CLOCK		D_S	P/S	P_n	*Q_n
MC14014B	MC14021B				
↑	X	X	1	0	0
↑	X	X	1	1	1

*Q6, Q7, & Q8 are available externally
X = Don't Care

LOGIC DIAGRAM



V_{DD} = Pin 16
V_{SS} = Pin 8
P4 = Pin 4
P5 = Pin 13

MC14014B•MC14021B

T-46-09-05

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	T_{low}* Min	T_{low}* Max	25°C Min	25°C Typ #	25°C Max	T_{high}* Min	T_{high}* Max	Unit
Output Voltage "0" Level	V_{OL}	5.0	–	0.05	–	0	0.05	–	0.05	Vdc
$V_{in} = V_{DD}$ or 0		10	–	0.05	–	0	0.05	–	0.05	
		15	–	0.05	–	0	0.05	–	0.05	
"1" Level	V_{OH}	5.0	4.95	–	4.95	5.0	–	4.95	–	Vdc
$V_{in} = 0$ or V_{DD}		10	9.95	–	9.95	10	–	9.95	–	
		15	14.95	–	14.95	15	–	14.95	–	
Input Voltage "0" Level	V_{IL}									Vdc
(V_O = 4.5 or 0.5 Vdc)		5.0	–	1.5	–	2.25	1.5	–	1.5	
(V_O = 9.0 or 1.0 Vdc)		10	–	3.0	–	4.50	3.0	–	3.0	
(V_O = 13.5 or 1.5 Vdc)		15	–	4.0	–	6.75	4.0	–	4.0	
"1" Level	V_{IH}									
(V_O = 0.5 or 4.5 Vdc)		5.0	3.5	–	3.5	2.75	–	3.5	–	Vdc
(V_O = 1.0 or 9.0 Vdc)		10	7.0	–	7.0	5.50	–	7.0	–	
(V_O = 1.5 or 13.5 Vdc)		15	11.0	–	11.0	8.25	–	11.0	–	
Output Drive Current (AL Device)	I_{OH}									mAdc
(V_{OH} = 2.5 Vdc) Source		5.0	−3.0	–	−2.4	−4.2	–	−1.7	–	
(V_{OH} = 4.6 Vdc)		5.0	−0.64	–	−0.51	−0.88	–	−0.36	–	
(V_{OH} = 9.5 Vdc)		10	−1.6	–	−1.3	−2.25	–	−0.9	–	
(V_{OH} = 13.5 Vdc)		15	−4.2	–	−3.4	−8.8	–	−2.4	–	
(V_{OL} = 0.4 Vdc) Sink	I_{OL}	5.0	0.64	–	0.51	0.88	–	0.36	–	mAdc
(V_{OL} = 0.5 Vdc)		10	1.6	–	1.3	2.25	–	0.9	–	
(V_{OL} = 1.5 Vdc)		15	4.2	–	3.4	8.8	–	2.4	–	
Output Drive Current (CL/CP Device)	I_{OH}									mAdc
(V_{OH} = 2.5 Vdc) Source		5.0	−2.5	–	−2.1	−4.2	–	−1.7	–	
(V_{OH} = 4.6 Vdc)		5.0	−0.52	–	−0.44	−0.88	–	−0.36	–	
(V_{OH} = 9.5 Vdc)		10	−1.3	–	−1.1	−2.25	–	−0.9	–	
(V_{OH} = 13.5 Vdc)		15	−3.6	–	−3.0	−8.8	–	−2.4	–	
(V_{OL} = 0.4 Vdc) Sink	I_{OL}	5.0	0.52	–	0.44	0.88	–	0.36	–	mAdc
(V_{OL} = 0.5 Vdc)		10	1.3	–	1.1	2.25	–	0.9	–	
(V_{OL} = 1.5 Vdc)		15	3.6	–	3.0	8.8	–	2.4	–	
Input Current (AL Device)	I_{in}	15	–	±0.1	–	±0.00001	±0.1	–	±1.0	µAdc
Input Current (CL/CP Device)	I_{in}	15	–	±0.3	–	±0.00001	±0.3	–	±1.0	µAdc
Input Capacitance (V_{in} = 0)	C_{in}	–	–	–	–	5.0	7.5	–	–	pF
Quiescent Current (AL Device) (Per Package)	I_{DD}	5.0	–	5.0	–	0.005	5.0	–	150	µAdc
		10	–	10	–	0.010	10	–	300	
		15	–	20	–	0.015	20	–	600	
Quiescent Current (CL/CP Device) (Per Package)	I_{DD}	5.0	–	20	–	0.005	20	–	150	µAdc
		10	–	40	–	0.010	40	–	300	
		15	–	80	–	0.015	80	–	600	
Total Supply Current**† (Dynamic plus Quiescent, Per Package) (C_L = 50 pF on all outputs, all buffers switching)	I_T	5.0	I_T = (0.75 µA/kHz) f + I_{DD}							µAdc
		10	I_T = (1.50 µA/kHz) f + I_{DD}							
		15	I_T = (2.25 µA/kHz) f + I_{DD}							

*T_{low} = −55°C for AL Device, −40°C for CL/CP Device.
T_{high} = +125°C for AL Device, +85°C for CL/CP Device.

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

**The formulas given are for the typical characteristics only at 25°C.

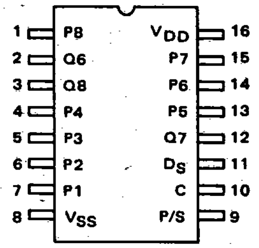
†To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50\ pF) + (C_L - 50)\ Vfk$$

where: I_T is in µA (per package), C_L in pF, V = ($V_{DD} - V_{SS}$) in volts, f in kHz is input frequency, and k = 0.0015.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in}$ or $V_{out}) \leq V_{DD}$.
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

PIN ASSIGNMENT



MC14014B•MC14021B

T-46-09-05

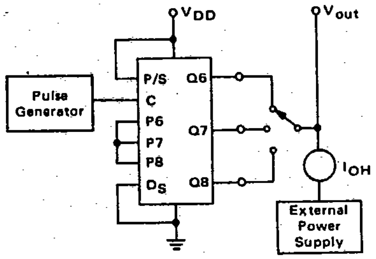
SWITCHING CHARACTERISTICS (C_L = 50 pF, T_A = 25°C)

Characteristic	Symbol	V_{DD} Vdc	Min	Typ #	Max	Unit
Output Rise and Fall Time	t_{TLH},					ns
t_{TLH}, t_{THL} = (1.5 ns/pF) C_L + 25 ns	t_{THL}	5.0	—	100	200	
t_{TLH}, t_{THL} = (0.75 ns/pF) C_L + 12.5 ns		10	—	50	100	
t_{TLH}, t_{THL} = (0.55 ns/pF) C_L + 9.5 ns		15	—	40	80	
Propagation Delay Time (Clock to Q, P/S to Q)	t_{PLH},					ns
t_{PHL}, t_{PLH} = (1.7 ns/pF) C_L + 315 ns	t_{PHL}	5.0	—	400	800	
t_{PHL}, t_{PLH} = (0.66 ns/pF) C_L + 137 ns		10	—	170	340	
t_{PHL}, t_{PLH} = (0.5 ns/pF) C_L + 90 ns		15	—	115	230	
Clock Pulse Width	t_{WH}	5.0	400	150	—	ns
		10	175	75	—	
		15	135	40	—	
Clock Frequency	f_{cl}	5.0	—	3.0	1.5	MHz
		10	—	6.0	3.0	
		15	—	8.0	4.0	
Parallel/Serial Control Pulse Width	t_{WH}	5.0	400	150	—	ns
		10	175	75	—	
		15	135	40	—	
Setup Time	t_{su}	5.0	200	100	—	ns
P/S to Clock		10	100	50	—	
		15	80	40	—	
Hold Time	t_h	5.0	20	−2.5	—	ns
Clock to P/S		10	20	−10	—	
		15	25	0	—	
Setup Time	t_{su}	5.0	350	150	—	ns
Data (Parallel or Serial) to		10	80	50	—	
Clock or P/S		15	60	30	—	
Hold Time	t_h	5.0	45	0	—	ns
Clock to D_s		10	35	0	—	
		15	35	5	—	
Hold Time	t_h	5.0	50	25	—	ns
Clock to P_n		10	45	20	—	
		15	45	20	—	
Input Clock Rise Time	$t_{r(cl)}$	5.0	—	—	15	µs
		10	—	—	5	
		15	—	—	4	

*The formulas given are for the typical characteristics only at 25°C.

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

FIGURE 1 – OUTPUT SOURCE CURRENT TEST CIRCUIT



Preset output under test to a logic "1" level.

FIGURE 2 – OUTPUT SINK CURRENT TEST CIRCUIT

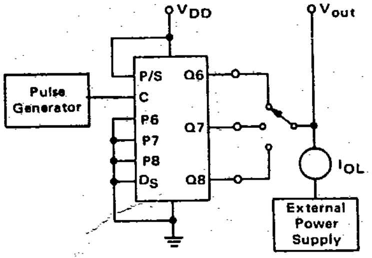


FIGURE 3 — POWER DISSIPATION TEST CIRCUIT AND WAVEFORM

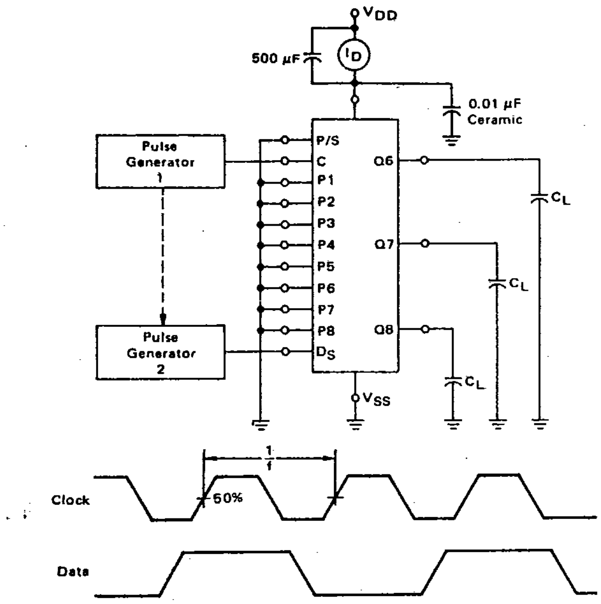
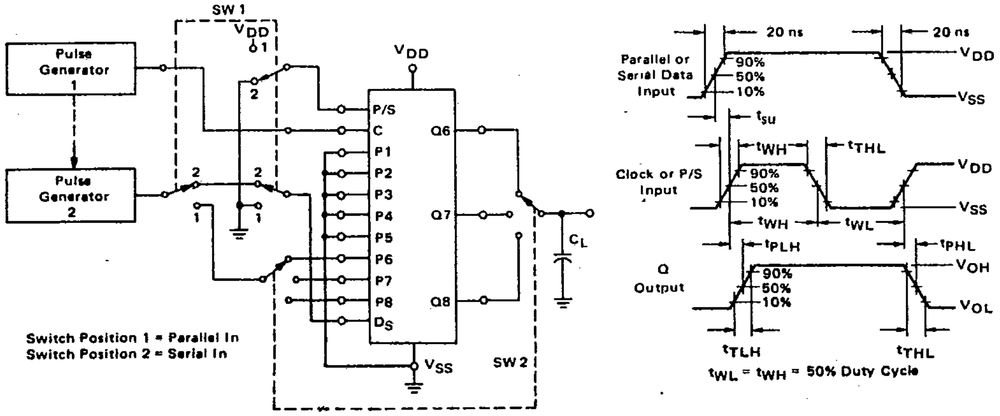


FIGURE 4 — SWITCHING TIME TEST CIRCUIT AND WAVEFORMS



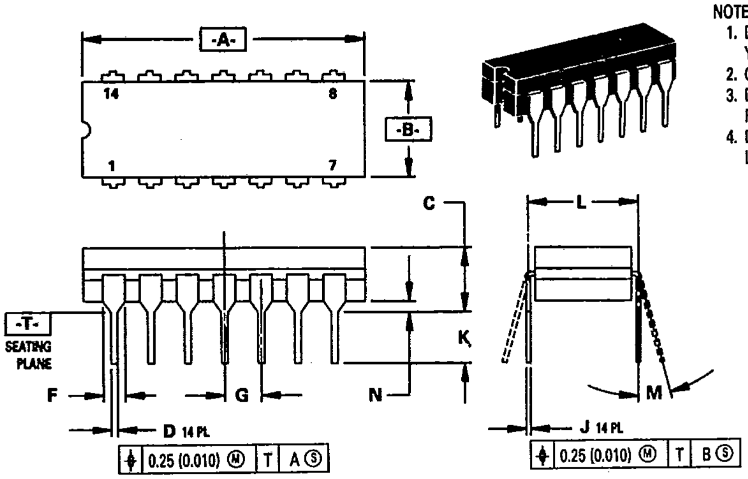
PACKAGE DIMENSIONS

T-90-20

The standard package availability for each device is indicated on the front page of the individual data sheets. Dimensions for the packages are given in this chapter. Surface mount packages may be special ordered by specifying the following suffixes: "D" (narrow SOIC), "DW" (wide SOIC), or "FN" (PLCC). For example, to order a quad NOR gate, use MC14001BD.

14-PIN PACKAGE

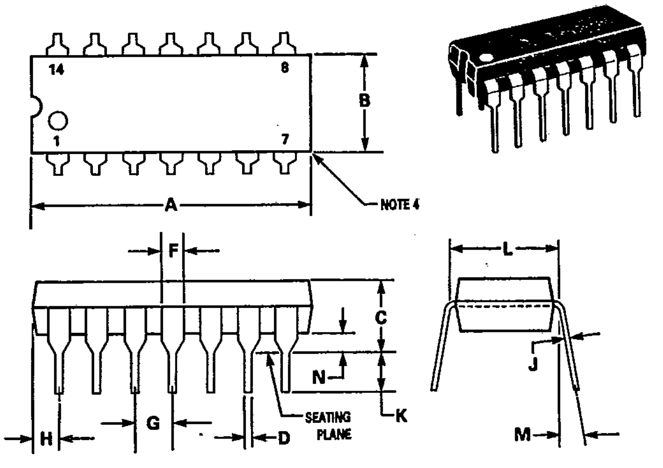
CERAMIC PACKAGE
CASE 632-08



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIM F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	19.05	19.94	0.750	0.785
B	6.23	7.11	0.245	0.280
C	3.94	5.08	0.155	0.200
D	0.39	0.50	0.015	0.020
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
J	0.21	0.38	0.008	0.015
K	3.18	4.31	0.125	0.170
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.01	0.020	0.040

PLASTIC PACKAGE
CASE 646-06



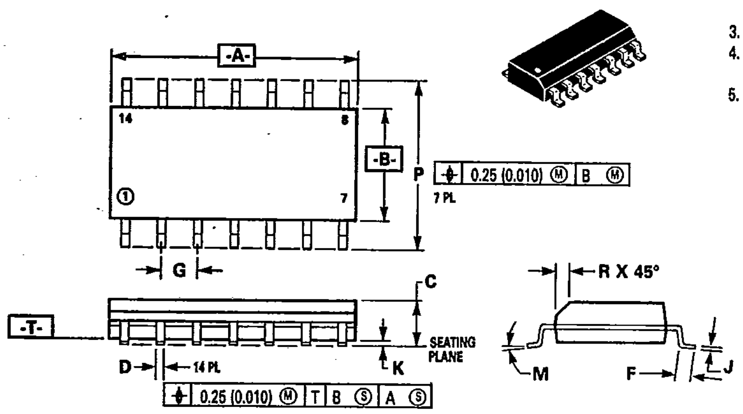
NOTES:
1. LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.
4. ROUNDED CORNERS OPTIONAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	18.16	19.56	0.715	0.770
B	6.10	6.60	0.240	0.260
C	3.69	4.69	0.145	0.185
D	0.38	0.53	0.015	0.021
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	1.32	2.41	0.052	0.095
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	10°	0°	10°
N	0.39	1.01	0.015	0.039

PACKAGE DIMENSIONS (Continued)

14-PIN PACKAGE

SOIC PACKAGE
CASE 751A-02
D SUFFIX



NOTES:

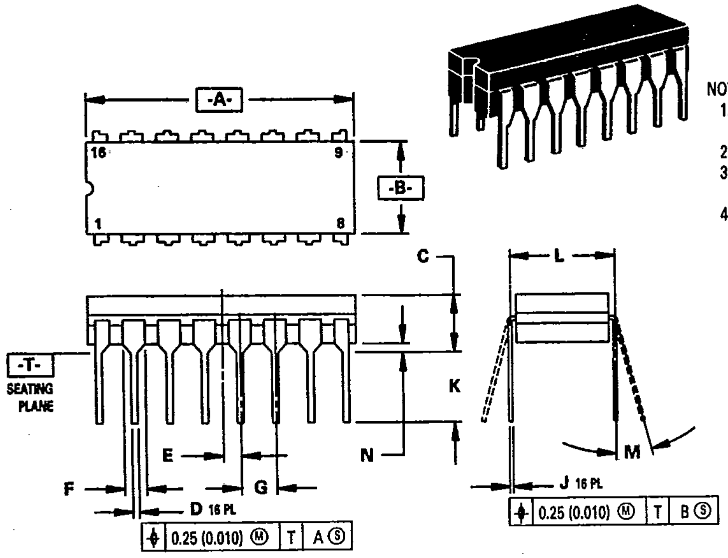
1. DIMENSIONS A AND B ARE DATUMS AND T IS A DATUM SURFACE.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
3. CONTROLLING DIMENSION: MILLIMETER.
4. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
5. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS (Continued)

16-PIN PACKAGE

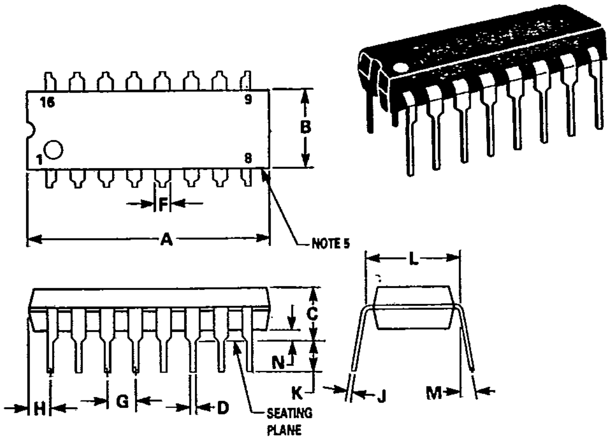
CERAMIC PACKAGE
CASE 620-09



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIM F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	19.05	19.55	0.750	0.770
B	6.10	7.36	0.240	0.290
C	—	4.19	—	0.165
D	0.39	0.53	0.015	0.021
E	1.27 BSC		0.050 BSC	
F	1.40	1.77	0.055	0.070
G	2.54 BSC		0.100 BSC	
J	0.23	0.27	0.009	0.011
K	—	5.08	—	0.200
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.39	0.88	0.015	0.035

PLASTIC PACKAGE
CASE 648-06



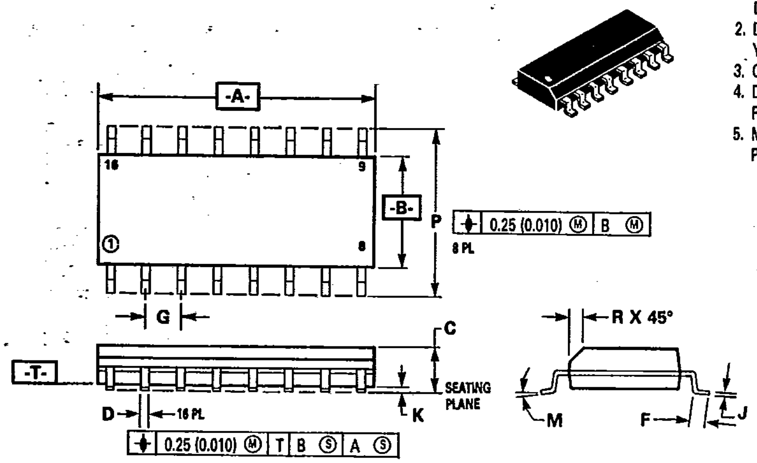
NOTES:
1. LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.
4. "F" DIMENSION IS FOR FULL LEADS.
5. ROUNDED CORNERS OPTIONAL.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	18.80	21.34	0.740	0.840
B	6.10	6.60	0.240	0.260
C	3.69	4.69	0.145	0.185
D	0.38	0.53	0.015	0.021
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	0.38	2.41	0.015	0.095
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	10°	0°	10°
N	0.39	1.01	0.015	0.040

PACKAGE DIMENSIONS (Continued)

16-PIN PACKAGE

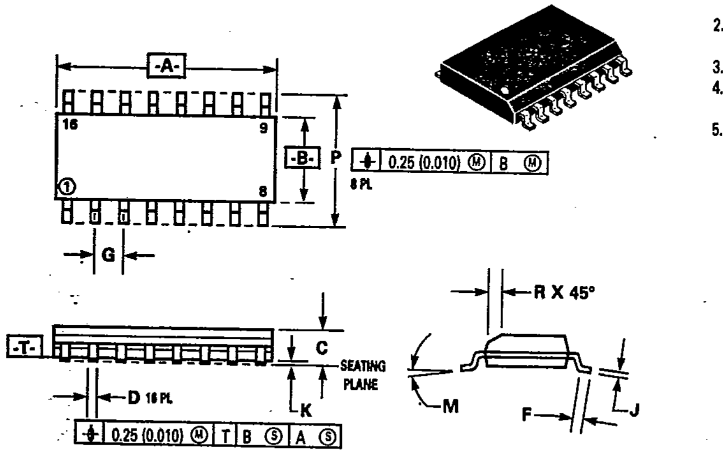
SOIC PACKAGE
CASE 751B-03
D SUFFIX



NOTES:
1. DIMENSIONS A AND B ARE DATUMS AND T IS A DATUM SURFACE.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
3. CONTROLLING DIMENSION: MILLIMETER.
4. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
5. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SOIC PACKAGE
CASE 751G-01
DW SUFFIX



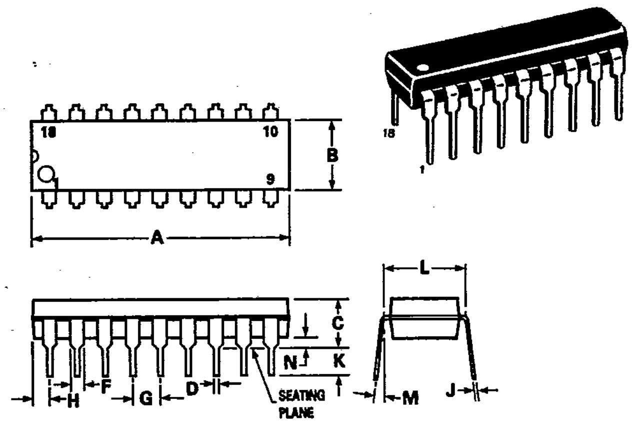
NOTES:
1. DIMENSIONS A AND B ARE DATUMS AND T IS A DATUM SURFACE.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
3. CONTROLLING DIMENSION: MILLIMETER.
4. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
5. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.26	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
	0.25	0.75	0.010	0.029

PACKAGE DIMENSIONS (Continued)

18-PIN PACKAGE

PLASTIC PACKAGE
CASE 707-02

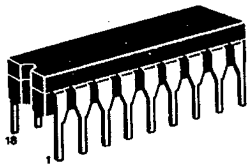


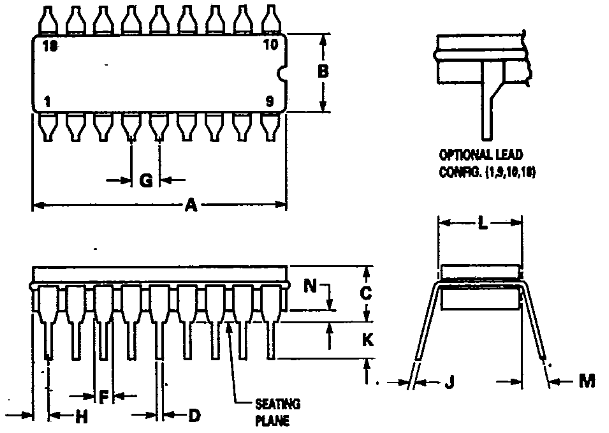
NOTES:

1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25mm(0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.22	23.24	0.875	0.915
B	6.10	6.60	0.240	0.260
C	3.56	4.57	0.140	0.180
D	0.36	0.56	0.014	0.022
F	1.27	1.78	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	1.02	1.52	0.040	0.060
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

CERAMIC PACKAGE
CASE 726-04





NOTES:

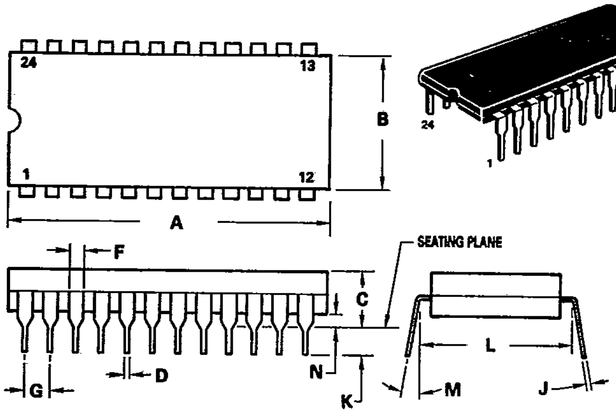
1. LEADS, TRUE POSITIONED WITHIN 0.25 mm (0.010) DIA. AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
2. DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIM "A" & "B" INCLUDES MENISCUS.
4. "F" DIMENSION IS FOR FULL LEADS. "HALF" LEADS ARE OPTIONAL AT LEAD POSITIONS 1, 9, 10, AND 18.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.35	23.11	0.880	0.910
B	6.10	7.49	0.240	0.295
C	—	5.08	—	0.200
D	0.38	0.53	0.015	0.021
F	1.40	1.78	0.055	0.070
G	2.54 BSC		0.100 BSC	
H	0.51	1.14	0.020	0.045
J	0.20	0.30	0.008	0.012
K	3.18	4.32	0.125	0.170
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

PACKAGE DIMENSIONS (Continued)

24-PIN PACKAGE

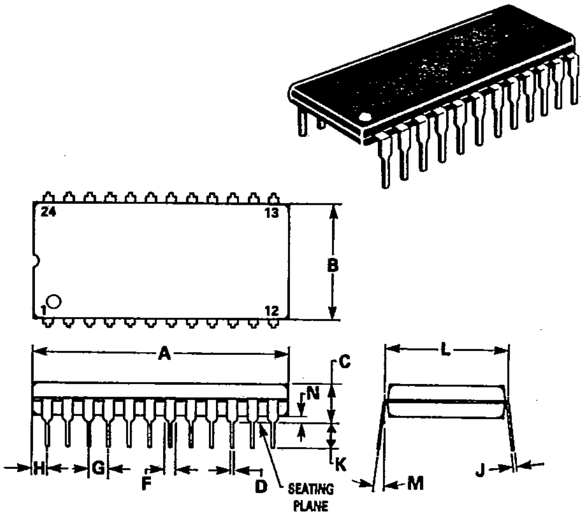
CERAMIC PACKAGE
CASE 623-05



NOTES:
1. DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
2. LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION. (WHEN FORMED PARALLEL).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	31.24	32.77	1.230	1.290
B	12.70	15.49	0.500	0.610
C	4.06	5.59	0.160	0.220
D	0.41	0.51	0.016	0.020
F	1.27	1.52	0.050	0.060
G	2.54 BSC		0.100 BSC	
J	0.20	0.30	0.008	0.012
K	3.18	4.06	0.125	0.160
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.27	0.020	0.050

PLASTIC PACKAGE
CASE 709-02



NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 mm (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	31.37	32.13	1.235	1.265
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.03	0.065	0.080
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040